

REWORKABLE EDGEBOND ADHESIVE

UA-2605 is a reworkable edgebond adhesive for BGA's, CSP's, and other surface mount components. The adhesive enhances drop and bend test performance as well as improves resistance against shock and vibration. The adhesive cures quickly at low temperature and exhibits excellent adhesion to organic substrates.

TYPICAL PROPERTIES

Color	Yellow
Filler Content, %	50
Viscosity (cps)	
SSA #14, 1 RPM, 25°C	220,000
Cure Conditions, minutes	
130°C	10
140°C	5
150°C	1
Specific Gravity	1.56
Shelf Life @ -5°C, months	12
Pot Life @ 25°C, days	14
CURED PROPERTIES	
CTE1, ppm/°C	30
CTE2, ppm/°C	104
Tg, °C (TMA)	134
Storage Modulus, GPa (DMA)	7.6
Volatiles Content, wt% loss on cure	<2.0

DIRECTIONS FOR USE

Dispense adhesive along the perimeter of the assembled component. Leave a small edge section unbonded so as not to completely seal the air under the chip. This is to ensure that there is an outlet for any expansion of the air during processing. DO NOT LEAVE ANY OF THE CORNERS UNBONDED. Cure according to the listed cure schedules. Recommended cure temperature is actual temperature of the adhesive. For other cure temperatures, consult your Zymet sales representative.

DIRECTIONS FOR REWORK

Heating the exposed adhesive fillet facilitates ease of removal. Use a heat resistant probe (i.e. orange stick) to scrape away the heated adhesive. Heat between 130°C -180°C. Use the lowest practical temperature and minimize the length of time at high temperature prior to removal. For more detailed instructions, contact your Zymet sales representative.

STORAGE AND HANDLING

Store at -5°C, or below. Thaw completely before use. Use good industrial hygiene to avoid skin and eye contact. Wash off affected area with soap and water.

Refer to MSDS before use or disposal.

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